

TAI-SAW TECHNOLOGY CO., LTD.

No. 3, Industrial 2nd Rd., Ping-Chen Industrial District, Taoyuan, 324, Taiwan, R.O.C. TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales@mail.taisaw.com Web: www.taisaw.com

Product Specifications Approval Sheet

Product Description: Dielectric Filter TST Parts No.: TR0117AA0090	lter 3450MHz BW 300MHz Size 15.9x5.1 mm
Customer Parts No.:	
Customer signature required	t
Company:	
Division:	
Approved by :	
Date:	
	Alam Class
Checked by:	Nina Chen
Approved by:	Nina Chen Nina Chen Kazuma Lee
Date:	

- 1. Customer signed back is required before TST can proceed with sample build and receive orders.
- 2. Orders received without customer signed back will be regarded as agreement on the specifications.
- 3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.



TAI-SAW TECHNOLOGY CO., LTD.

No. 3, Industrial 2nd Rd., Ping-Chen Industrial District, Taoyuan, 324, Taiwan, R.O.C. TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales@mail.taisaw.com Web: www.taisaw.com

Dielectric Filter 3450MHz BW 300MHz Size 15.9x5.1mm

MODEL NO.: TR0117AA0090 REV. NO.:1.0

A. Maximum Rating:

1. Input Power:10W

2. Operating Temperature: -40°C to +105°C

3. Storage Temperature: 0°C to +40°C

4. Moisture Sensitivity Level: 2a(MSL 2a)

RoHS Compliant Lead free Lead-free soldering

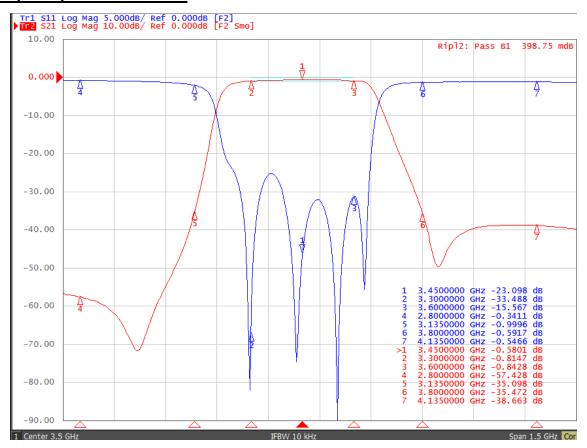
Electrostatic Sensitive Device (ESD)

B. <u>Electrical Characteristics</u>:

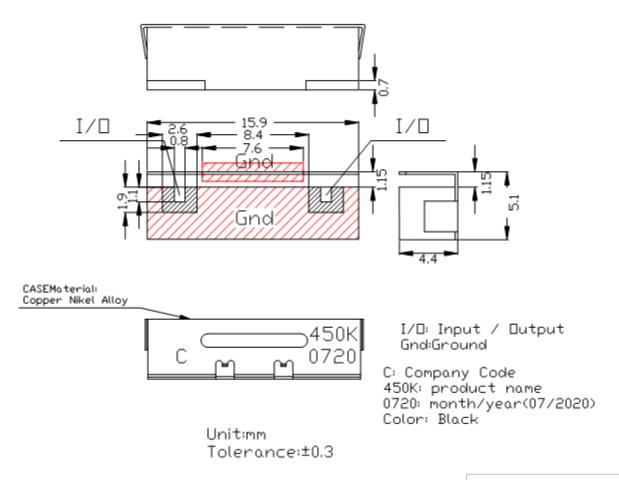
ITEM		SPECIFICATION		
		Min	Тур	Max
INSERTION LOSS	3300~3600 MHz		1.5 dB	2.0 dB
RIPPLE	3300~3600 MHz		0.6 dB	1.0 dB
RETURN LOSS	3300~3600 MHz	10 dB		
ATTENUATION	2800 ~ 3135 MHz	30 dB		
	3800 ~ 4135 MHz	30 dB		

ATTENUATION specifies the absolute value of attenuation.

C. Frequency Characteristics:

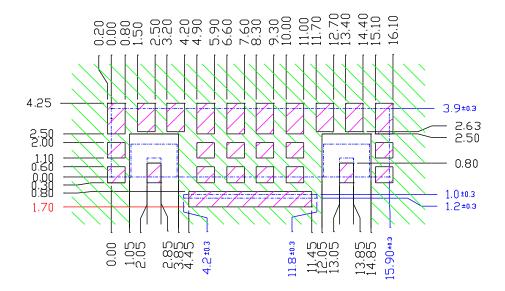


D. <u>Dimension</u>:



E. PCB Footprint:

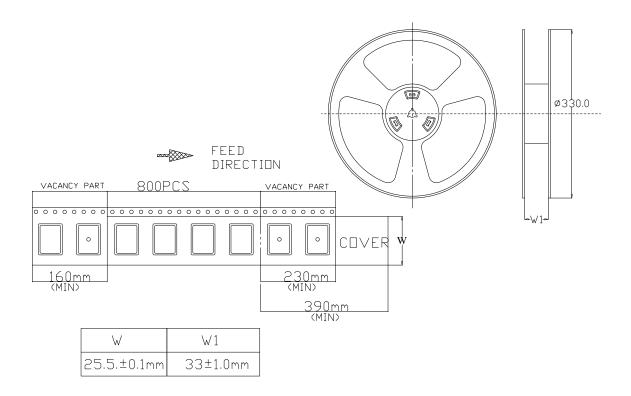
PCB Layout

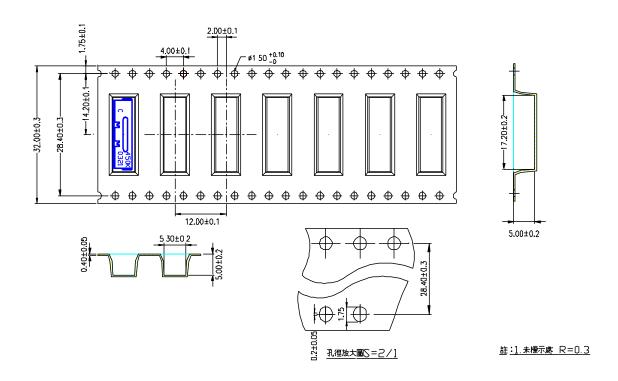


unit:mm Tolerance:±0.1

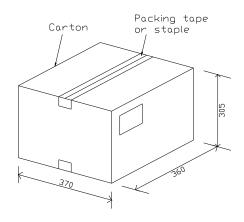
Solder Resist Over Conductor	Solder Resist Over Dielectric
Exposed	filter outline

F.Packing:

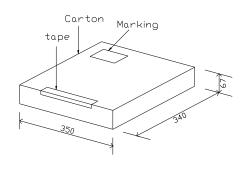




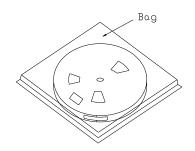
Outer Carton
 Quanyity:3200PCS



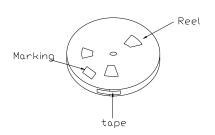
2. Inner Carton Quanyity:800PCS



3. Bag Quanyity:800PCS



4. Taping Quanyity:800PCS



Unit:mm

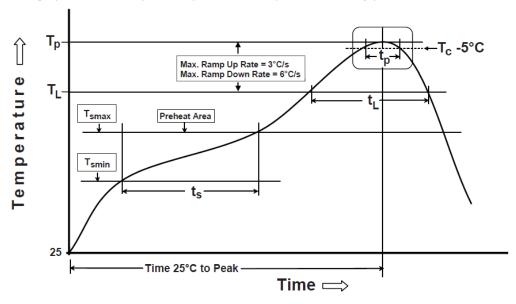
G. Recommended Reflow Profile:

Products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 3 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°℃	to Peak Temperature	8 minutes max.
Composition of se	older paste	96.5Sn/3Ag/0.5Cu
Solder Paste Mod	el	SHENMAO PF606-P26

Note: All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature 270 ± 10 °C.

Apply preheating at 120° C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature $270\pm10^{\circ}$ C or 3 seconds, it will make component surface peeling or damage. Soldering iron can not leakage of electricity.